



# IMPORTANT NOTICE

10 December 2015

## 1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors

## 1. General description

Planar passivated very sensitive gate four quadrant triac in a SOT54 plastic package intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

## 2. Features and benefits

- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drivers and microcontrollers
- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Very sensitive gate

## 3. Applications

- General purpose low power phase control
- General purpose low power switching
- Solid-state relay

## 4. Quick reference data

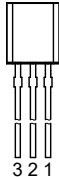
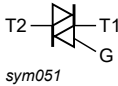
Table 1. Quick reference data

| Symbol                        | Parameter                            | Conditions                                                                                                              | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------------|-------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
| $V_{DRM}$                     | repetitive peak off-state voltage    |                                                                                                                         | -   | -   | 600 | V    |
| $I_{T(RMS)}$                  | RMS on-state current                 | full sine wave; $T_{lead} \leq 50\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | -   | -   | 0.6 | A    |
| $I_{TSM}$                     | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>   | -   | -   | 8   | A    |
|                               |                                      | full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$                                                   | -   | -   | 8.8 | A    |
| $T_j$                         | junction temperature                 |                                                                                                                         | -   | -   | 125 | °C   |
| <b>Static characteristics</b> |                                      |                                                                                                                         |     |     |     |      |
| $I_{GT}$                      | gate trigger current                 | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                      | -   | 1   | 5   | mA   |
|                               |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                      | -   | 2   | 5   | mA   |
|                               |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                      | -   | 2   | 5   | mA   |

| Symbol                         | Parameter                             | Conditions                                                                                                                                                       | Min | Typ | Max | Unit             |
|--------------------------------|---------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------------------|
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                                                | -   | 4   | 7   | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>                                                                                  | -   | 1   | 10  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 0.85\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>                                                                               | -   | 1.4 | 1.9 | V                |
| <b>Dynamic characteristics</b> |                                       |                                                                                                                                                                  |     |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 402\text{ V}$ ; $T_j = 110\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit; <a href="#">Fig. 12</a> | 30  | 45  | -   | V/ $\mu\text{s}$ |
| $dV_{com}/dt$                  | rate of change of commutating voltage | $V_D = 600\text{ V}$ ; $T_j = 50\text{ }^\circ\text{C}$ ; $dI_{com}/dt = 0.3\text{ A/ms}$ ; $I_T = 0.84\text{ A}$ ; gate open circuit                            | -   | 5   | -   | V/ $\mu\text{s}$ |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description     | Simplified outline                                                                                  | Graphic symbol                                                                                 |
|-----|--------|-----------------|-----------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------|
| 1   | T2     | main terminal 2 | <br>TO-92 (SOT54) | <br>sym051 |
| 2   | G      | gate            |                                                                                                     |                                                                                                |
| 3   | T1     | main terminal 1 |                                                                                                     |                                                                                                |

6. Ordering information

Table 3. Ordering information

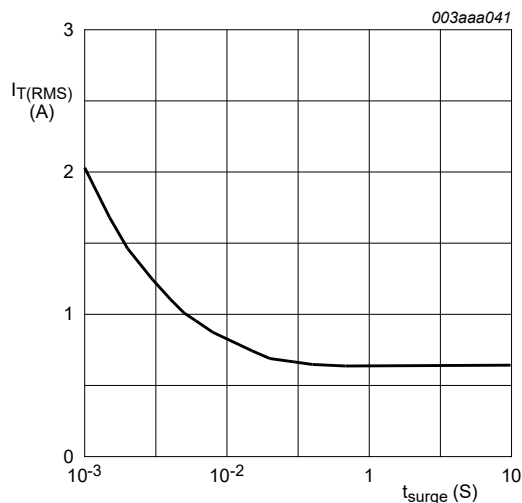
| Type number | Package |                                                             |         |
|-------------|---------|-------------------------------------------------------------|---------|
|             | Name    | Description                                                 | Version |
| MAC97A8     | TO-92   | plastic single-ended leaded (through hole) package; 3 leads | SOT54   |

## 7. Limiting values

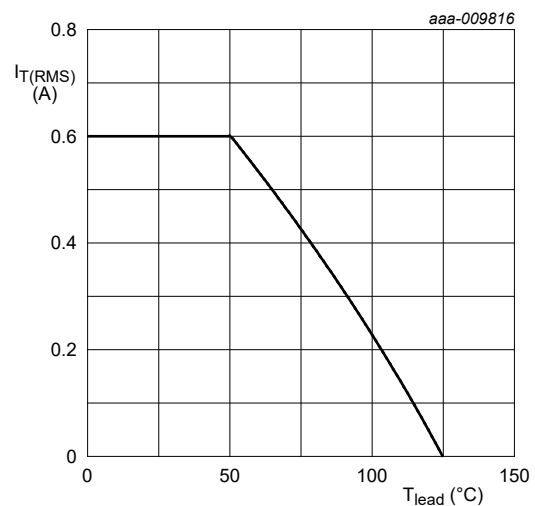
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol              | Parameter                            | Conditions                                                                                                         | Min | Max  | Unit                   |
|---------------------|--------------------------------------|--------------------------------------------------------------------------------------------------------------------|-----|------|------------------------|
| $V_{\text{DRM}}$    | repetitive peak off-state voltage    |                                                                                                                    | -   | 600  | V                      |
| $I_{\text{T(RMS)}}$ | RMS on-state current                 | full sine wave; $T_{\text{lead}} \leq 50\text{ }^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3                         | -   | 0.6  | A                      |
| $I_{\text{TSM}}$    | non-repetitive peak on-state current | full sine wave; $T_{\text{j(init)}} = 25\text{ }^{\circ}\text{C}$ ; $t_{\text{p}} = 20\text{ ms}$ ; Fig. 4; Fig. 5 | -   | 8    | A                      |
|                     |                                      | full sine wave; $T_{\text{j(init)}} = 25\text{ }^{\circ}\text{C}$ ; $t_{\text{p}} = 16.7\text{ ms}$                | -   | 8.8  | A                      |
| $I^2t$              | $I^2t$ for fusing                    | $t_{\text{p}} = 10\text{ ms}$ ; SIN                                                                                | -   | 0.32 | $\text{A}^2\text{s}$   |
| $di_{\text{T}}/dt$  | rate of rise of on-state current     | $I_{\text{G}} = 10\text{ mA}$                                                                                      | -   | 50   | $\text{A}/\mu\text{s}$ |
|                     |                                      |                                                                                                                    | -   | 50   | $\text{A}/\mu\text{s}$ |
|                     |                                      | $I_{\text{G}} = 14\text{ mA}$                                                                                      | -   | 10   | $\text{A}/\mu\text{s}$ |
|                     |                                      | $I_{\text{G}} = 10\text{ mA}$                                                                                      | -   | 50   | $\text{A}/\mu\text{s}$ |
| $I_{\text{GM}}$     | peak gate current                    | $t = 2\text{ microseconds (max)}$                                                                                  | -   | 1    | A                      |
| $P_{\text{GM}}$     | peak gate power                      |                                                                                                                    | -   | 5    | W                      |
| $P_{\text{G(AV)}}$  | average gate power                   | $T(\text{lead}) \leq 80\text{ }^{\circ}\text{C}$ ; $t = 2\text{ microseconds (max)}$                               | -   | 0.1  | W                      |
| $T_{\text{stg}}$    | storage temperature                  |                                                                                                                    | -40 | 150  | $^{\circ}\text{C}$     |
| $T_{\text{j}}$      | junction temperature                 |                                                                                                                    | -   | 125  | $^{\circ}\text{C}$     |



**Fig. 1. RMS on-state current as a function of surge duration; maximum values**



**Fig. 2. RMS on-state current as a function of lead temperature; maximum values**

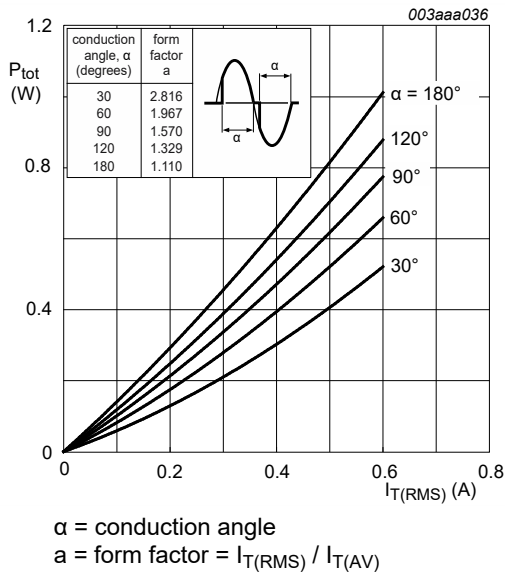


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

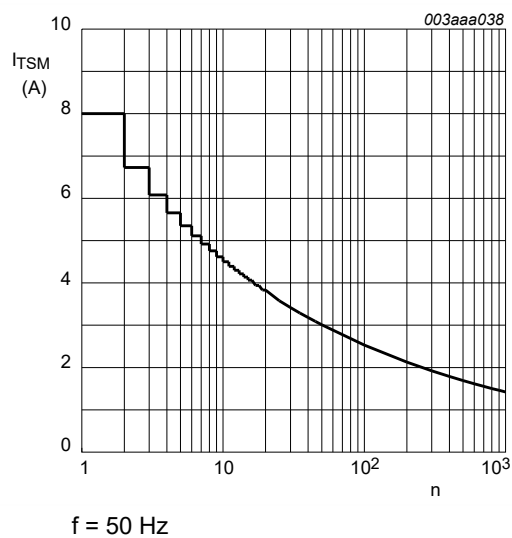
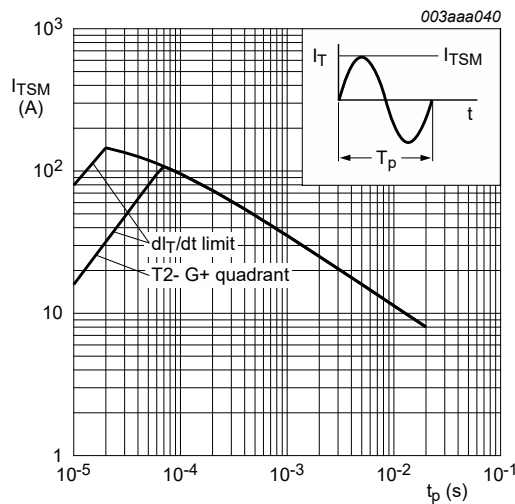


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



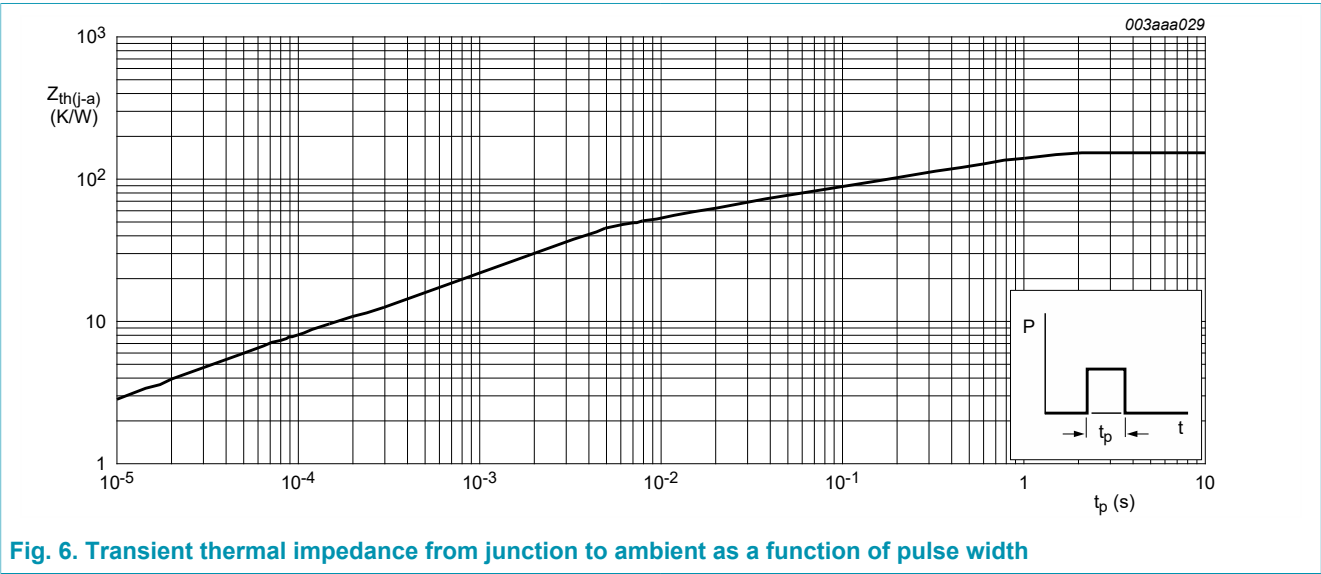
$t_p \leq 20$  ms

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

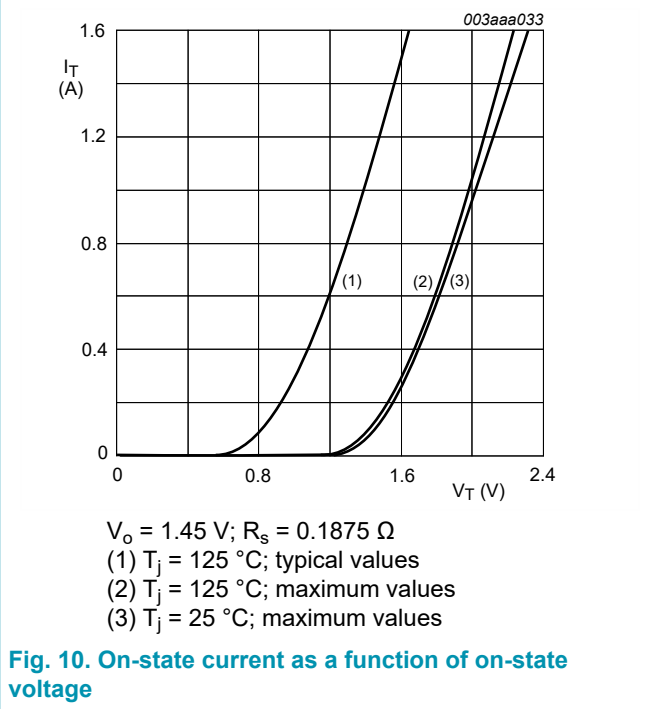
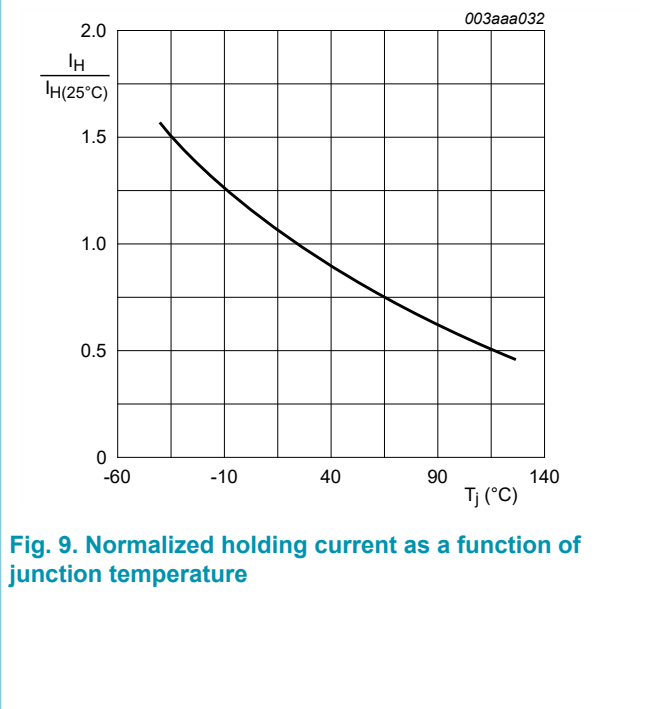
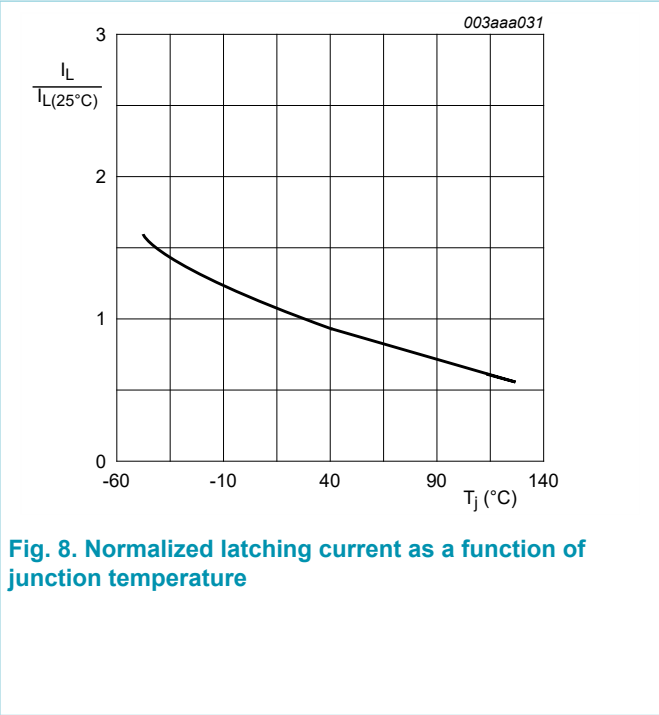
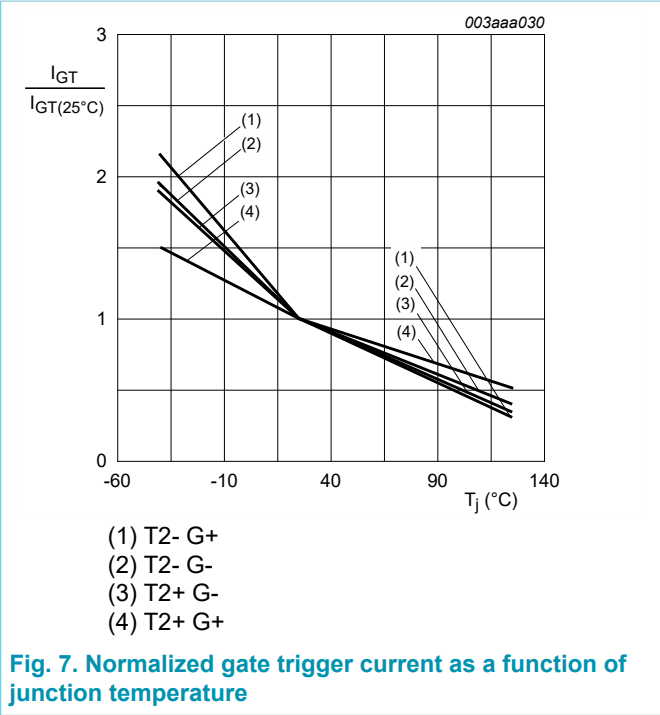
| Symbol           | Parameter                                            | Conditions                                        |  | Min | Typ | Max | Unit |
|------------------|------------------------------------------------------|---------------------------------------------------|--|-----|-----|-----|------|
| $R_{th(j-lead)}$ | thermal resistance from junction to lead             | full cycle; Fig. 6                                |  | -   | -   | 60  | K/W  |
|                  |                                                      | half cycle                                        |  | -   | -   | 80  | K/W  |
| $R_{th(j-a)}$    | thermal resistance from junction to ambient free air | printed circuit board mounted: lead length = 4 mm |  | -   | 150 | -   | K/W  |



## 9. Characteristics

Table 6. Characteristics

| Symbol                         | Parameter                             | Conditions                                                                                                                                                       |  | Min | Typ | Max | Unit             |
|--------------------------------|---------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|-----|-----|-----|------------------|
| <b>Static characteristics</b>  |                                       |                                                                                                                                                                  |  |     |     |     |                  |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                                                |  | -   | 1   | 5   | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                                                |  | -   | 2   | 5   | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                                                |  | -   | 2   | 5   | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                                                |  | -   | 4   | 7   | mA               |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                                                |  | -   | 1   | 10  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                                                |  | -   | 5   | 10  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                                                |  | -   | 1   | 10  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                                                |  | -   | 2   | 10  | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>                                                                                  |  | -   | 1   | 10  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 0.85\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>                                                                               |  | -   | 1.4 | 1.9 | V                |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                                                       |  | -   | 0.9 | 1.5 | V                |
|                                |                                       | $V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 110\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                                                     |  | 0.1 | 0.7 | -   | V                |
| $I_D$                          | off-state current                     | $V_D = 600\text{ V}$ ; $T_j = 110\text{ }^\circ\text{C}$                                                                                                         |  | -   | 3   | 100 | $\mu\text{A}$    |
| <b>Dynamic characteristics</b> |                                       |                                                                                                                                                                  |  |     |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 402\text{ V}$ ; $T_j = 110\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit; <a href="#">Fig. 12</a> |  | 30  | 45  | -   | V/ $\mu\text{s}$ |
| $dV_{com}/dt$                  | rate of change of commutating voltage | $V_D = 600\text{ V}$ ; $T_j = 50\text{ }^\circ\text{C}$ ; $dI_{com}/dt = 0.3\text{ A/ms}$ ; $I_T = 0.84\text{ A}$ ; gate open circuit                            |  | -   | 5   | -   | V/ $\mu\text{s}$ |
| $t_{gt}$                       | gate-controlled turn-on time          | $I_{TM} = 1\text{ A}$ ; $V_D = 600\text{ V}$ ; $I_G = 25\text{ mA}$ ; $dI_G/dt = 5\text{ A}/\mu\text{s}$                                                         |  | -   | 2   | -   | $\mu\text{s}$    |





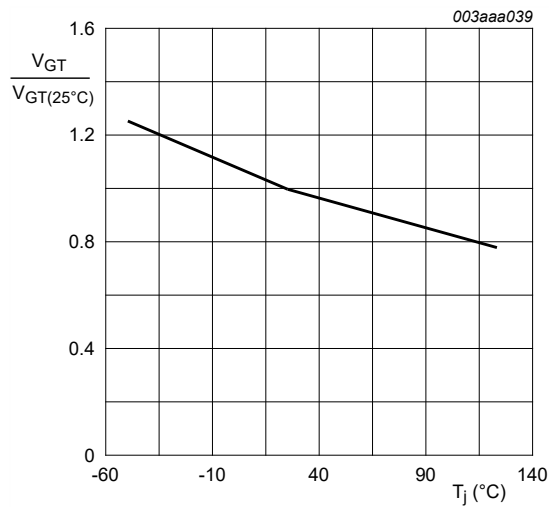


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

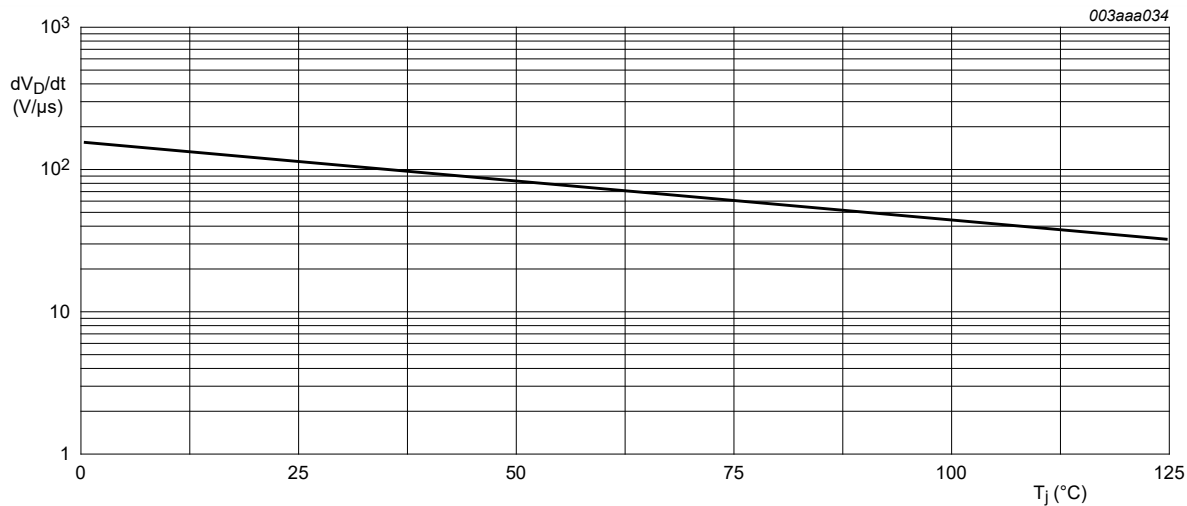


Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

10. Package outline

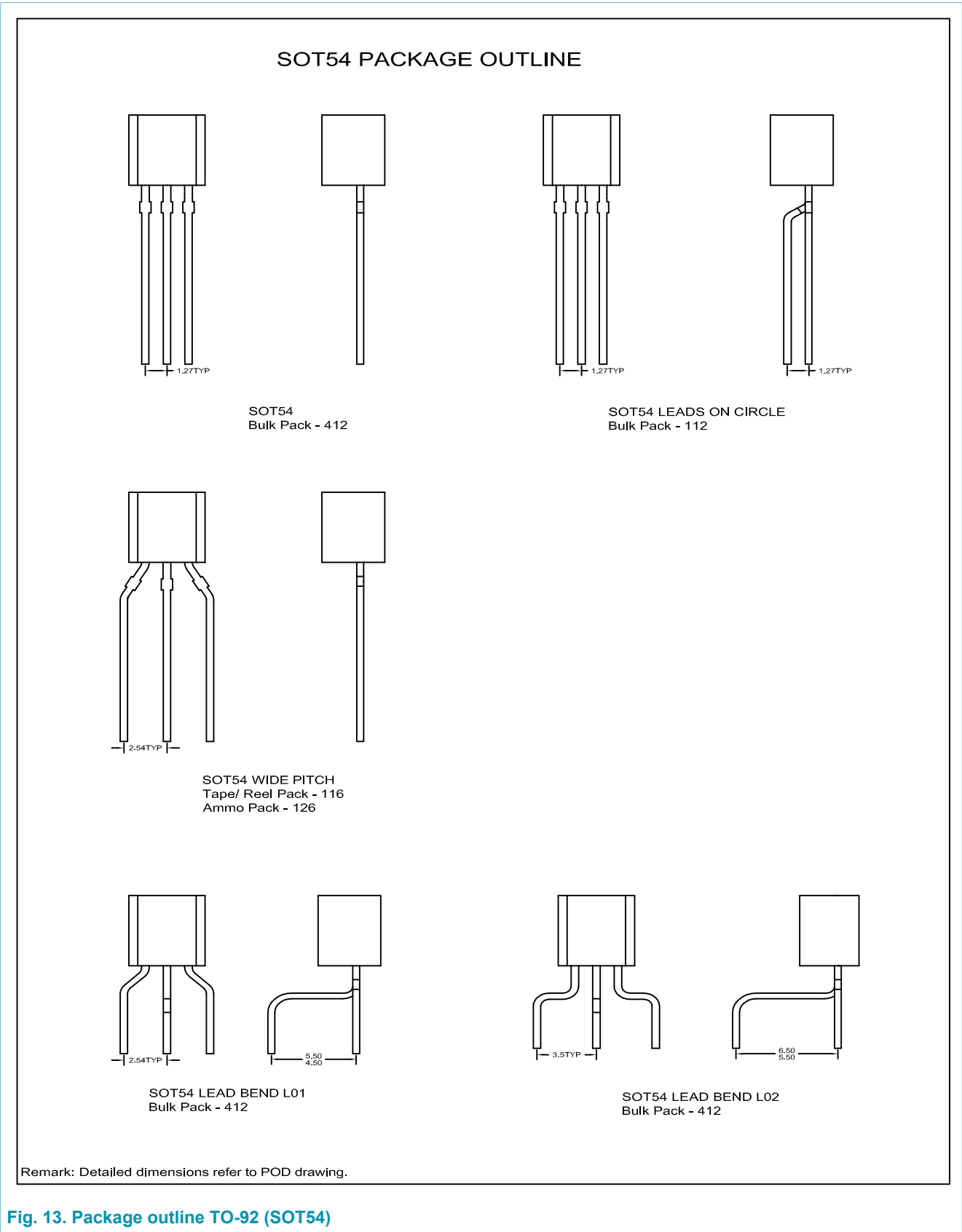


Fig. 13. Package outline TO-92 (SOT54)

## 11. Legal information

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| Document status [1][2]         | Product status [3] | Definition                                                                            |
|--------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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